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Freescale Semiconductor
Data Sheet: Product Preview

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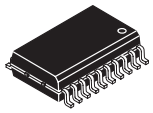
MC33690



SOIC-20

MC33690 Standalone Tag Reader Circuit

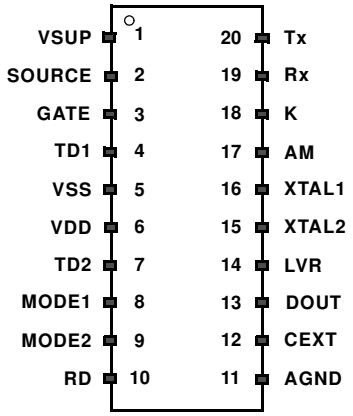
The standalone tag reader circuit (STARC) is an integrated circuit dedicated to the automotive immobilizer applications. It combines the antenna drivers and demodulator necessary to interface with a transponder.

A low dropout voltage regulator and a physical interface fully compatible with the ISO 9141 norm are also available.

The STARC is fabricated with the SMARTMOSTM3.5 technology. This process is a double layer metal 1.4µm 45V technology, combining CMOS and bipolar devices.

- Contactless 125 kHz tag reader module:
  - Self synchronous sample and hold demodulator
  - Amplitude or phase modulation detection
  - High sensitivity
  - Fast read after write demodulator settling time
  - Low resistance and high current antenna drivers, 2W @ 150mA (typ.)
  - Bidirectionnal data transmission
  - Multi-tag, multi-scheme operation
- Low dropout voltage regulator:
  - Wide input supply voltage range from 5.5V up to 40V
  - Output current capability up to 150mA DC with an external power transistor
  - 5V output voltage with a ±5% accuracy
  - Low voltage reset function
  - Low current consumption in standby mode:
  - 300µA (typ.)
- ISO 9141 transmitter and receiver module:
  - Input voltage thresholds ratiometric to the supply voltage
  - Current limitation
  - Output slew rate control
  - No external protection device required

Pin Connections



ORDERING INFORMATION

Device	Operating Junction Temperature Range	Package
MC33690DW	T_J = –40°C to 125°C	SOIC 20
MC33690DWE	TJ = –40°C to 125°C	SOIC 20 (ROHS)

This document contains information on a product under development. Freescale reserves the right to change or discontinue this product without notice.

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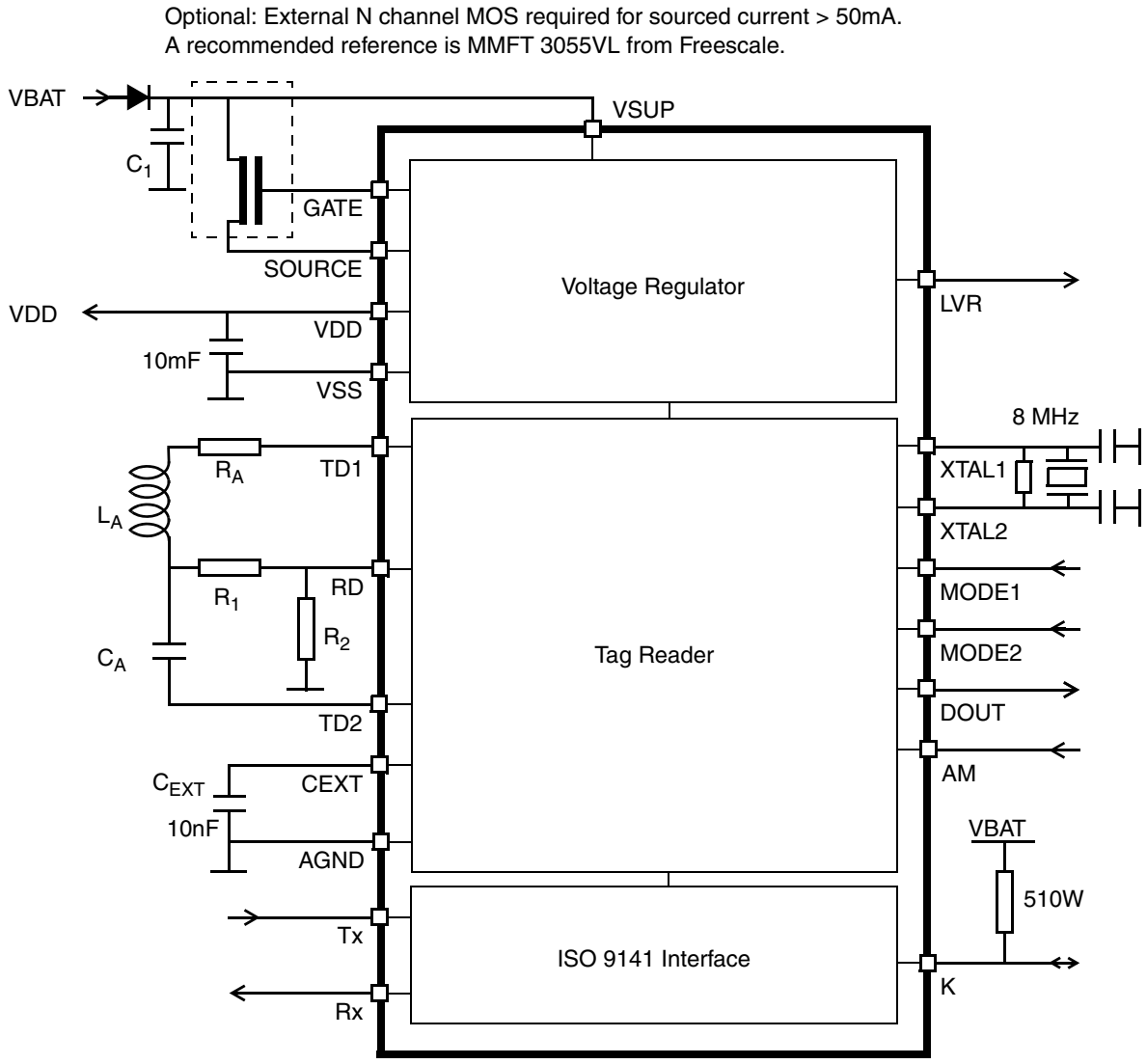


Figure 1. Standalone Tag Reader Circuit

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Supply voltage	V_{SUP}	V_{SS} −0.3 to +40	V
Supply voltage without using the voltage regulator (V_{SUP} = V_{DD})	V_{DD}	V_{SS} −0.3 to +7	V
Voltage on SOURCE	—	V_{SS} −0.3 to +40	V
Current into/from GATE	—	0	mA
Voltage on GATE	—	V_{SS} −0.3	V
Voltage on pins: MODE1/2, CEXT, DOUT, LVR, XTAL1/2, Rx, Tx	—	V_{SS} −0.3 to V_{DD} +0.3	V
Voltage on RD	—	±10	V
Voltage on K and AM	—	V_{SS} −3 to 40	V
Current on TD1 and TD2 (Drivers on and off)	—	±300	mA
Voltage on AGND	—	V_{SS} ±0.3	V
ESD voltage capability[1]	—	±2000	V
ESD voltage capability[1]	—	±200	V
Solder heat resistance test (10s)	—	260	°C
Junction temperature	T_J	170	°C
Storage temperature	T_s	−65 to +150	°C

[1] Human Body Model, AEC-Q100-002 Rev. C; Machine Model, AEC-Q100-003 Rev. E.

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Junction to ambient thermal resistance (SOIC20)	R_{th}	80	°C/W

Table 3. Pin Function Descriptions

Pin	Function	Description
1	VSUP	Power supply
2	SOURCE	External N channel transistor source
3	GATE	External N channel transistor gate
4	TD1	Antenna driver 1 output
5	VSS	Power and digital ground
6	VDD	Voltage regulator output
7	TD2	Antenna driver 2 output
8	MODE1	Mode selection input 1
9	MODE2	Mode selection input 2
10	RD	Demodulator input

Table 3. Pin Function Descriptions (continued)

11	AGND	Demodulator ground
12	CEXT	Comparator reference input
13	DOUT	Demodulator output (5V)
14	LVR	Low Voltage Reset input/output
15	XTAL2	Oscillator output
16	XTAL1	Oscillator input
17	AM	Amplitude modulation input
18	K	ISO 9141 transmitter output and receiver input
19	Rx	ISO 9141 receiver monitor output
20	Tx	ISO 9141 transmitter input

1 Description

1.1 Tag Reader Module

The tag reader module is dedicated for automotive or industrial applications where information has to be transmitted contactless.The tag reader module is a write/read (challenge/response) controller for applications that a demand high security level.

The tag reader module is connected to a serial-tuned LC circuit that generates a magnetic field power supplying the tag. The use of a synchronous sample and hold technique allows communication with all available tags using admittance switching producing absorption of the RF field.

Load amplitude or phase shift modulation can be detected at high bit rates up to 8 kHz. The typical operational carrier frequency of the tag reader module with an 8 MHz clock is 125 kHz.

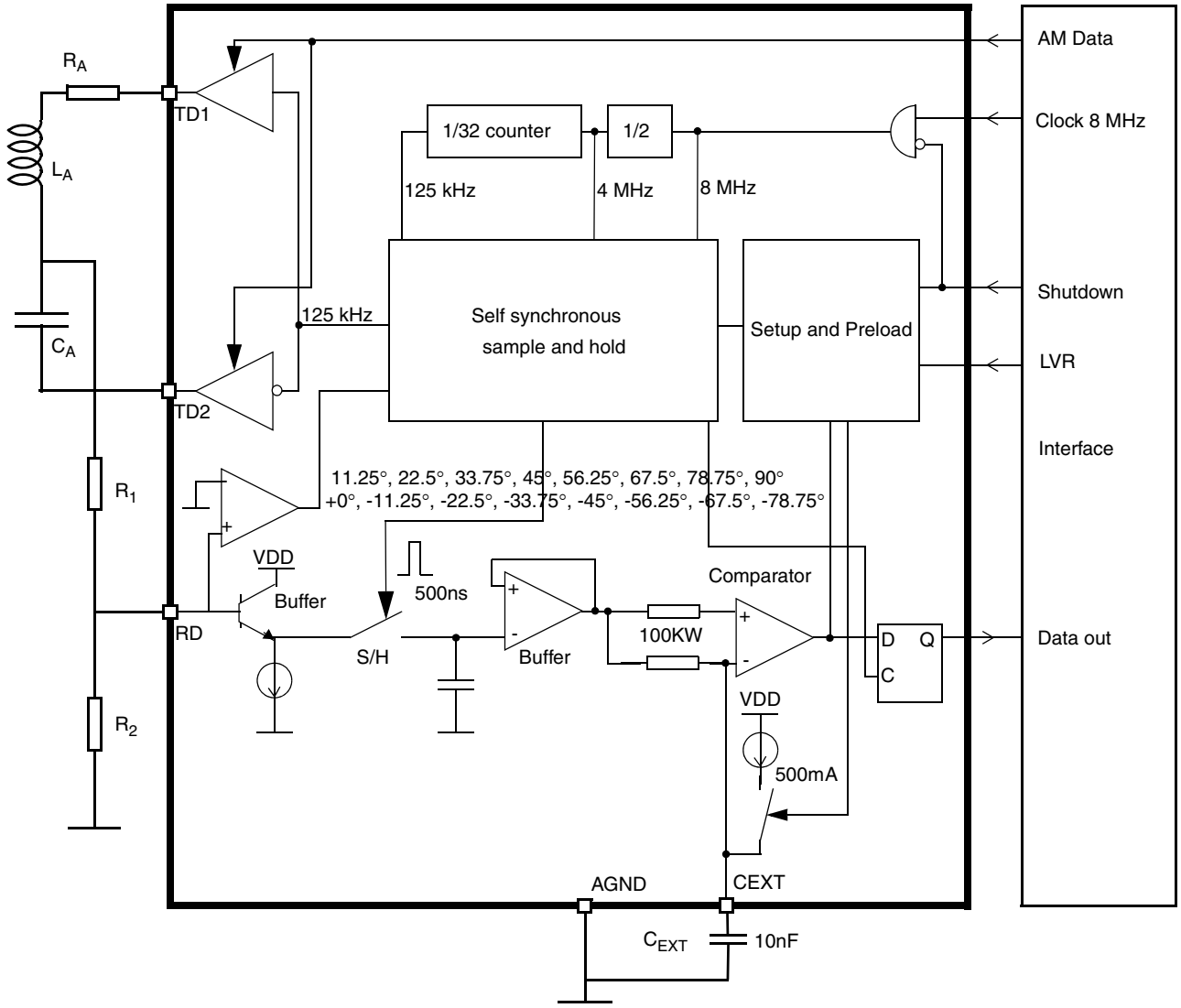


Figure 2. Tag Reader Block Diagram

2 Read Function

When answering to the base station, a transponder generates an absorption modulation of the magnetic field. It results in an amplitude/phase modulation of the current across the antenna. This information is picked up at the antenna tap point between the coil and the capacitor. An external resistive ladder down scales this voltage to a level compatible with the demodulator input voltage range (see Section 15, “Tag Reader”).

The demodulator (see Figure 2) consists of:

- an input stage (emitter follower)
- a sample and hold circuit
- a voltage follower
- a low offset voltage comparator

The sampling time is automatically set to take into account a phase shift due to the tolerances of the antenna components (L and C) and of the oscillator. The allowed phase shift measured at the input RD ranges from –45° to +45°. Assuming that the phase

reference is the falling edge of the driving signal TD1, this leads to a sampling time phase ranging from –78.75° to 90° with discrete steps of 11.25°. After reset condition, the sampling time phase is +11.25°.

The antenna phase shift evaluation is only done after each wake-up command or after reset. This is necessary to obtain the best demodulator performances.

To ensure a fast demodulator settling time after wake-up, reset, or a write sequence, the external capacitor CEXT is preloaded at its working voltage. This preset occurs 256µs after switching the antenna drivers on and its duration is 128µs. After wake-up or reset, the preset has the same duration, but begins 518µs after clock settling. After power on reset, VSUP must meet the minimum specified value, enabling the nominal operation of VDD, before the start of the preset. Otherwise, the preset must be done through a standby/wake-up sequence.

3 Write Function

Whatever the selected configuration (see Section 6, “Communication Modes Description”), the write function is achieved by switching on/off the output drivers TD1/2. After the drivers have been set in high impedance, the load current flows alternatively through the internal diodes to VSS and to VDD (see Figure 3).

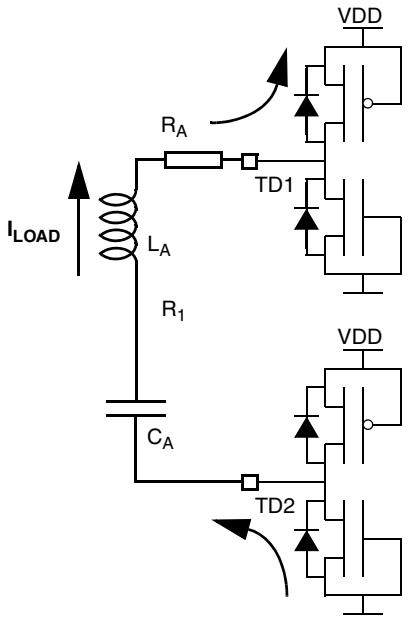


Figure 3. Current Flow When Buffers are Switched Off

4 Voltage Regulator

The low dropout voltage regulator provides a regulated 5V supply for the internal circuitry. It can also supply external peripherals or sensors. The input supply voltage ranges from 5.5V to over 40V.

This voltage regulator uses a series combination of high voltage LDMOS and low voltage PMOS transistors to provide regulation. An external low ESR capacitor is required for the regulator stability.

The maximum average current is limited by the power dissipation capability of the SO 20 package. This limitation can be overcome by connecting an external N channel MOS parallel with the internal LDMOS. The threshold voltage of this transistor must be lower than the one of the internal LDMOS (1.95V typ.) to prevent the current from flowing into the LDMOS. Its breakdown voltage must be higher than the maximum supply voltage.

A low-voltage reset function monitors the VDD output. An internal 10µA pull-up current source allows, when an external capacitor is connected between LVR and GND, to generate delays at power up (5ms typ. with C_{Reset}=22nF). The LVR pin is

also the input generating the internal reset signal. Applying a logic low level on this pin resets the circuit, all the internal flip flops are reset, and drivers TD1/2 are switched on.

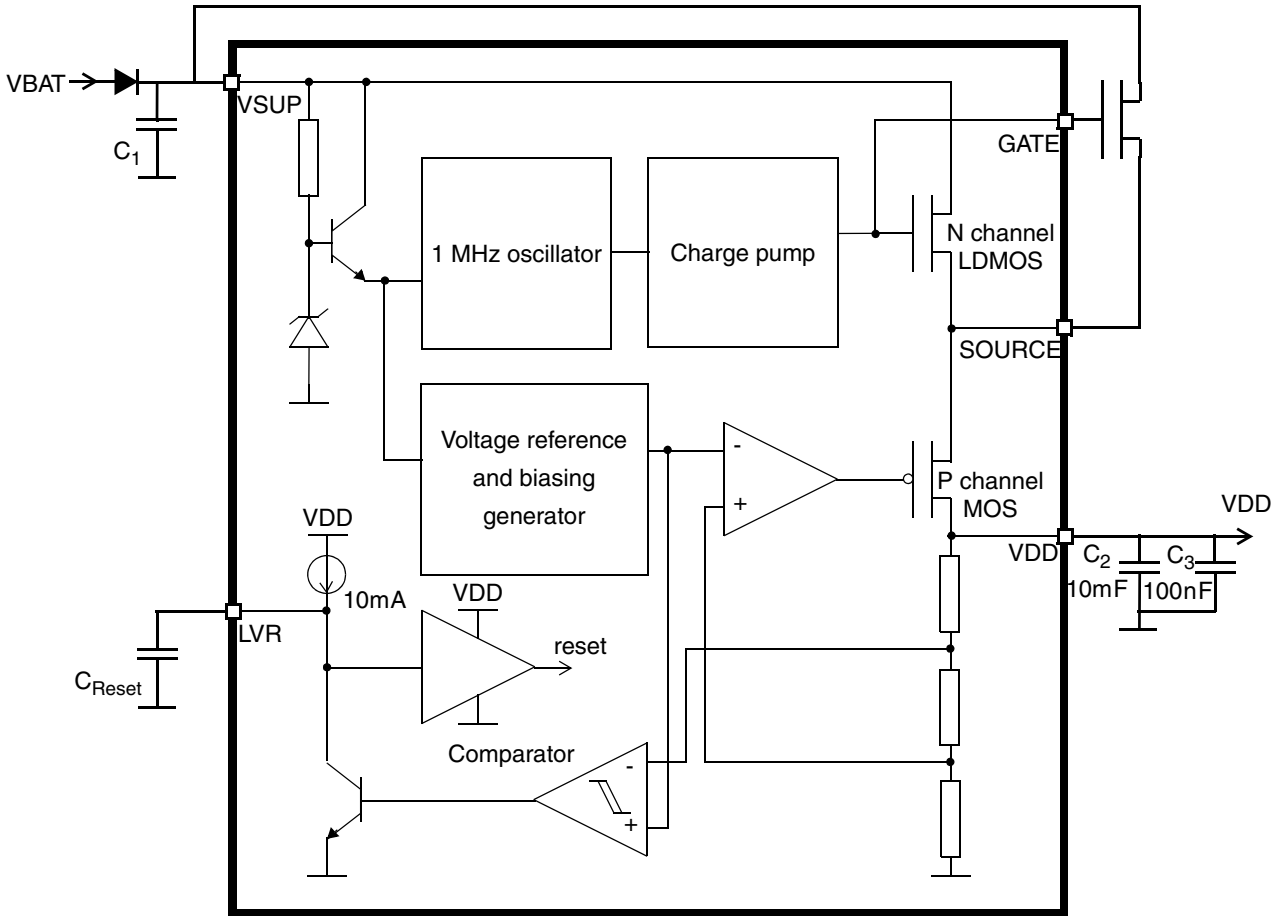


Figure 4. Voltage Regulator Block Diagram

5 ISO 9141 Physical Interface

This interface module is fully compatible with the ISO 9141 norm describing the diagnosis line. It includes one transmitter (pin K) and two receivers (pins K and AM).

The input stages consist of high-voltage CMOS triggers. The thresholds are ratiometric to VSUP. A ground referenced current source (2.5µA typ.) pulls down the input when unconnected.

When a negative voltage is applied on the K or AM lines, the input current is internally limited by a 2kΩ resistor (typ.) in series with a diode.

A current limitation allows the transmitter to drive any capacitive load and protects against short circuit to the battery voltage. An overtemperature protection shuts the driver down when the junction temperature exceeds 150°C (typ). After shutdown by the overtemperature protection, the driver can be switched on again if the junction temperature has decreased below the threshold and by applying an off/on command, coming from the demodulator in configurations A and B, or directly applied on the input Tx in configuration C (see Table 4).

The electromagnetic emission is reduced because of the voltage slew rate control (5V/µs typ.).

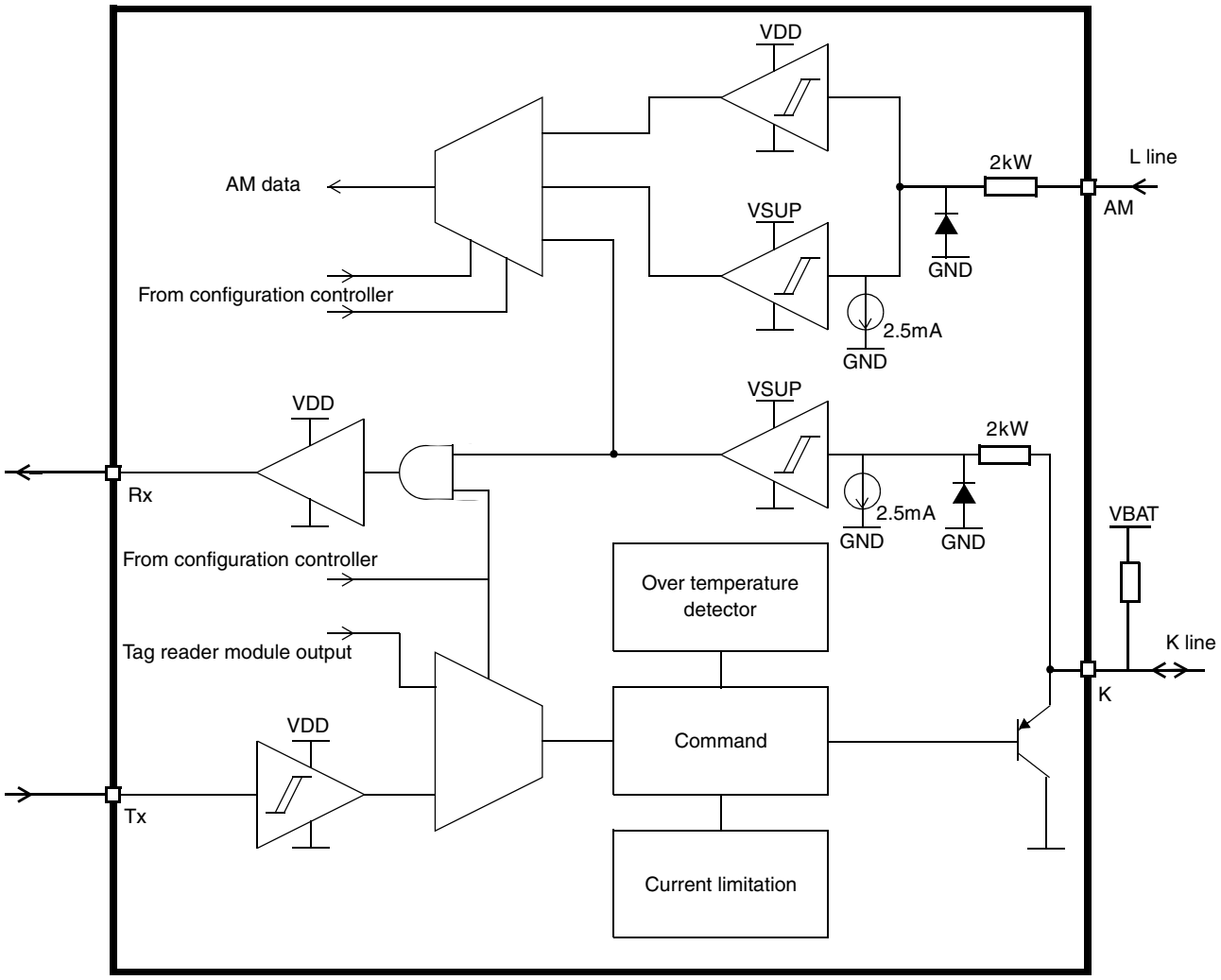


Figure 5. ISO 9141 Interface

6 Communication Modes Description

The STARC offers three different communication modes. Therefore, it can be used as a standalone circuit connected to an electronic control unit (ECU) through a bus line or it can be directly connected to a microcontroller in case of a single board architecture.

Table 4. Communication Modes Description

Configuration			Configuration Pins		Pin Status Function Description
Type	**Bus Type**	**Name**	**Mode1**	**Mode2**	
Standalone	1 wire (VBAT)	A	0	0	K output/input: • demodulator output • amplitude modulation input • shutdown/wake-up AM must be connected to VSUP DOUT forces a low level
	2 wires (VBAT)	B	0	1	K output: • demodulator output AM input: • amplitude modulation input • shutdown/wake-up DOUT forces a low level
Direct Connection to a MCU	2 wires (VDD)	C	1	x	DOUT output: • demodulator output AM input: • amplitude modulation input MODE2 input: • shutdown/wake-up
				1	K output/input (standalone ISO 9141 interface): • driven by Tx and monitored by Rx
				0	K input (standalone ISO 9141 interface): • monitored by Rx • Tx disabled

7 Standalone Configuration with One-Wire Bus

When a low level is applied on pins MODE1 and MODE2, the circuit is in configuration A (see Figure 24). After power on, the circuit is set into read mode. The demodulator output is directly routed to the ISO 9141 interface output K.

The circuit can be set into write mode at anytime by violation of all possible patterns on the single wire bus during more than 1ms. Then, the K line achieves the amplitude modulation by switching on/off both antenna drivers.

After 1ms of inactivity at the end of the challenge phase (bus in idle recessive one state), the circuit is set back into read mode.

The circuit can be put into standby mode by forcing the K line at zero during more than 2 ms after entering the write mode. After the K line is released, the circuit sends an acknowledge pulse before entering into standby mode. In standby mode, the oscillator and most of the internal biasing currents are switched off. Therefore, the functions (tag reader, ISO 9141 driver) are inactive except the voltage regulator and the ISO 9141 receiver on pin K. The driver output TD1 forces a low level and TD2 forces a high level. A rising edge on K wakes up the circuit. After completion of the wake-up sequence, the circuit is automatically set in read mode.

In configuration A, DOUT and Rx outputs always force a low level and Tx is disabled.

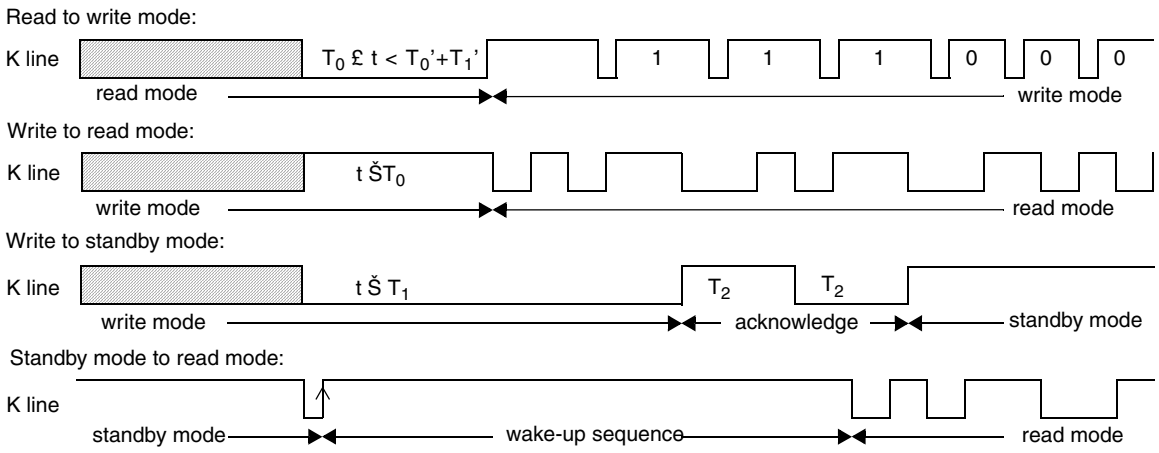


Figure 6. Mode Access Description in One-Wire Bus Configuration

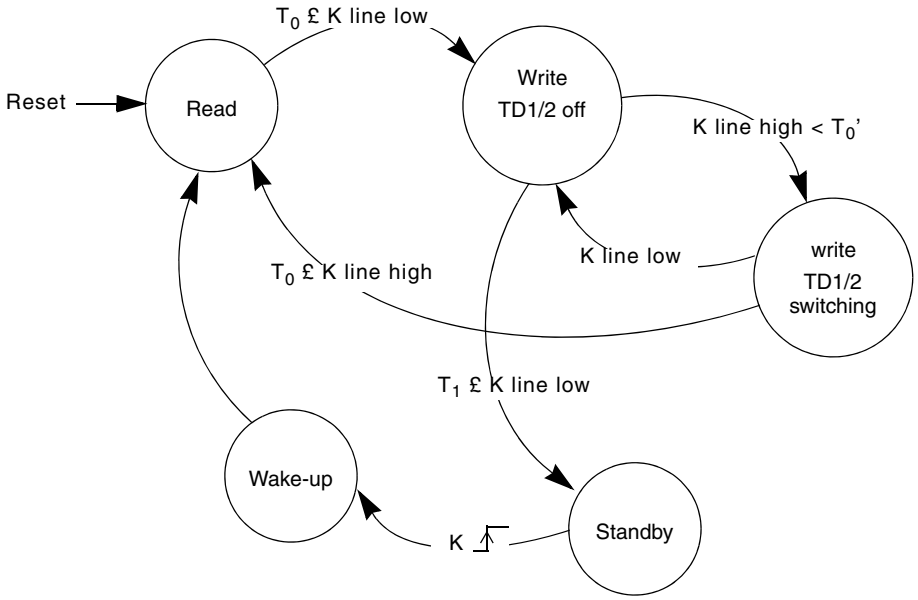


Figure 7. Configuration A State Diagram

7.1 Timing Definitions for a 8 MHz Crystal

The timing definitions for a 8 MHz crystal are:

- T_{ref} is crystal oscillator period (125 ns typ.)
- T_0=8064.T_{ref} = 1.008ms typ.
- T_0'=7932.T_{ref} = 0.992ms typ.
- T_1=16256.T_{ref} = 2.032ms typ.
- T_1'=16128.T_{ref} = 2.016ms typ.
- T_2=4096.T_{ref}, = 512µs typ.

T_0 is the minimum time required to guarantee the device toggles from read to write (or from write to read). However, the STARC may toggle from read to write (or from write to read) between T_0 and T_0'.

T_1 is the minimum time required to guarantee the device toggles from write to standby. However, the STARC may toggle in standby between T_1 and T_1'.

8 Standalone Configuration with Two-Wire Bus

When a low level is applied on MODE1 and a high level on MODE2, the circuit is in configuration B (see Figure 25). The K pin is set as an output sending the demodulated data.

The AM pin is set as a VSUP referenced input pin receiving the amplitude modulation and the shutdown/wake-up commands. Forcing high and low levels on AM achieves the amplitude modulation by switching on/off both antenna drivers. This amplitude modulation can be monitored on the K output and allows antenna short and open circuit diagnosis. The circuit can be put into standby mode by forcing the AM line at zero during more than 2 ms. The circuit sends an acknowledge pulse before entering into standby mode.

In standby mode, the oscillator and most of the internal biasing currents are switched off. Therefore, the functions (tag reader and ISO 9141 driver) are inactive except for the voltage regulator and the ISO 9141 receiver on pin AM. The driver output TD1 forces a low level and TD2 a high level. A rising edge on AM wakes up the circuit. After completion of the wake-up sequence, the circuit is automatically set in read mode.

In configuration B, DOUT and Rx outputs always force a low level and Tx is disabled.

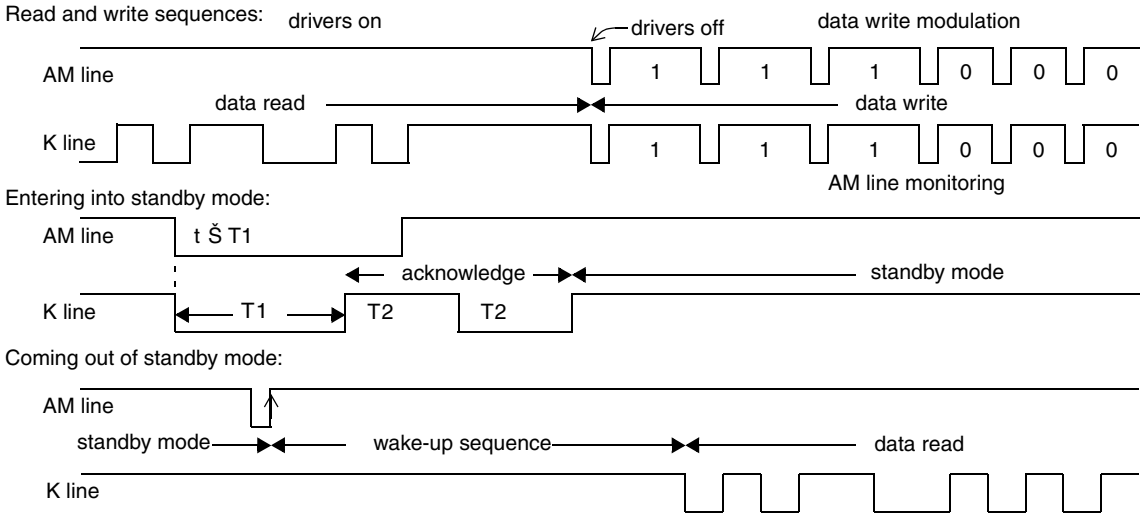


Figure 8. Modes Access Description in Two-wire Bus Configuration

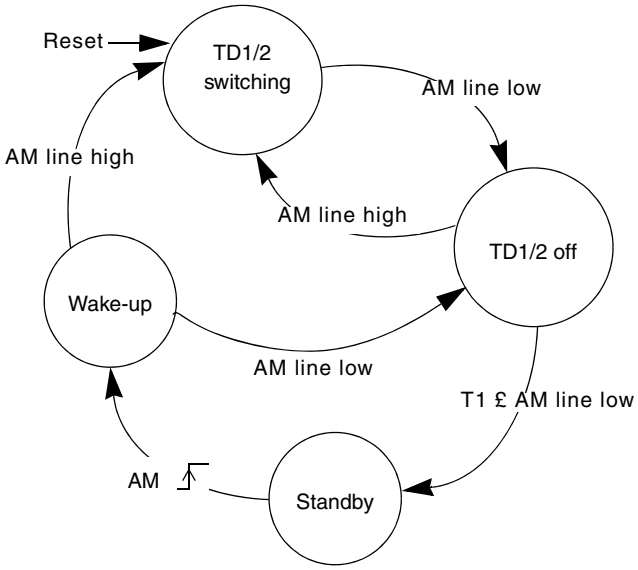


Figure 9. Configuration B State Diagram

9 Direct Connection to a Microcontroller Configuration

When a high level is applied on MODE1, the circuit is in configuration C (see Figure 26). The demodulated data are sent through DOUT.

The AM pin is set as a VDD referenced input pin receiving the AM command. Forcing high and low levels on AM achieves the amplitude modulation by switching on/off both antenna drivers. Meanwhile, this amplitude modulation can be monitored on DOUT. This allows antenna short and open circuit diagnosis.

The circuit can be put into standby mode by applying a low level on the MODE2 pin. In standby mode, the oscillator and most of the internal biasing currents are switched off. Therefore, the functions (tag reader and ISO 9141 interface) are inactive except for the voltage regulator. The driver outputs TD1 and TD2 are frozen in their state (high or low level) before entering into standby mode. DOUT forces a low level.

The ISO 9141 interface K is standalone and can be directly controlled by the input pin Tx and monitored by the output Rx. Applying a logic high level on Tx switches the output driver K on (dominant zero state when an external pull-up resistor is connected between K and VBAT). Applying a logic low level turns the driver off (one recessive state).

Rx monitors the voltage at the K pin. When the voltage is below the low threshold voltage, Rx forces a logic low level. When the voltage is above the high threshold voltage, Rx forces a logic high level.

In standby mode, Tx is disabled and Rx output monitors the voltage at the K pin.

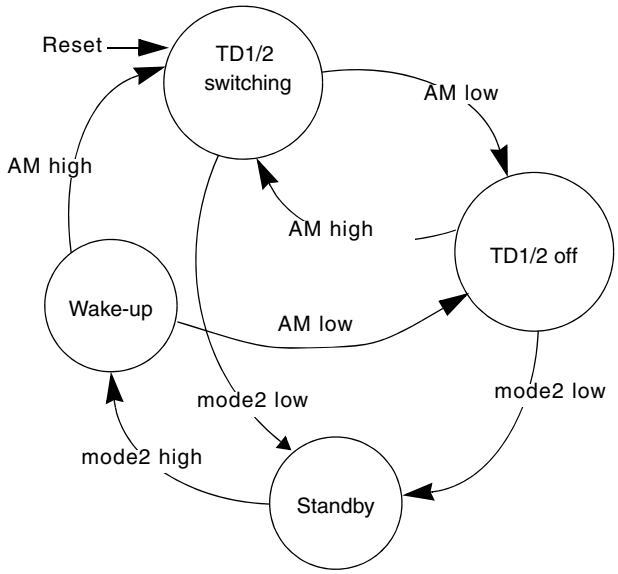


Figure 10. Configuration C State Diagram

10 Electrical Characteristics

Typical values reflect average measurements at V_{SUP}=12V and T_J=25°C.

11 Supply Current

Typical values reflect average measurements at 6V ≤ V_{SUP} ≤ 16V, V_{SS} = 0V, T_J = –40°C to +125°C, unless otherwise noted.

Table 5. Supply Current Specifications

Parameter		Symbol	Test Conditions and Comments	Min	Typ	Max	Unit	Type
Pin VSUP								
9.1	Standby mode current	I_{SUP1}	—	—	300	500	µA	—
9.2	Operating mode current	I_{SUP2}	Circuit in configuration C No current sunk from VDD Drivers TD1/2 switched off Tx forced to low	—	1.5	2.5	mA	—

12 Voltage Regulator

Typical values reflect average measurements at $6V \le V_{SUP} \le 16V$, $V_{SS} = 0V$, $T_J = –40°C$ to $+125°C$, unless otherwise noted

Table 6. Voltage Regulator Specifications

Parameter		Symbol	Test Conditions and Comments	Min	Typ	Max	Unit	Type
Pins VSUP and VDD								
1.1	Output Voltage ($5.5V \le V_{SUP} \le 40V$)	V_{VDD1}	Without external MOS transistor, $I_{OUT} \le 50mA$	4.75	5.0	5.25	V	—
1.3	Total Output Current	I_{VDD1}		—	—	50	mA	—
1.5	Load Regulation	$V_{LoadReg1}$	Without external MOS transistor, 1 to 50mA I_{OUT} change	—	20	60	mV	—
1.9	Output Voltage ($5.5V \le V_{SUP} \le 40V$)	V_{VDD2}	With external MOS transistor, $I_{OUT} \le 150mA$ The stability is ensured with a decoupling capacitor between VDD and VSS: $C_{OUT} \ge 10\mu F$ with $ESR \le 3\Omega$. The current capability can be increased up to 150mA by using an external N channel MOS transistor (see Figure 1). The main characteristics for choosing this component are VT < 1.8V and BVDSS > 40V	4.7	5.0	5.3	V	—
1.11	Total Output Current	I_{VDD2}		—	—	150	mA	—
1.6	Load Regulation	$V_{LoadReg2}$	With external MOS transistor,1 to 150mA I_{OUT} change	—	65	150	mV	—
1.4	Line Regulation ($6V \le V_{SUP} \le 16V$)	$V_{LineReg}$	$I_{OUT} = 1mA$	—	—	—	mV	—

13 Low-Voltage Reset

Typical values reflect average measurements at $6V \le V_{SUP} \le 16V$, $V_{SS} = 0V$, $T_J = –40°C$ to $+125°C$, unless otherwise noted

Table 7. Low-Voltage Reset Specifications

Parameter		Symbol	Test Conditions and Comments	Min	Typ	Max	Unit	Type
Pin LVR								
1.6	Low Voltage Reset Low Threshold	V_{LVRON}	Because the voltage regulator and the low-voltage reset are using the same internal voltage reference, the low-voltage reset occurs only when the voltage regulator is out of regulation. See Figure 11	4.1	4.35	4.6	V	—
1.7	Low Voltage Reset Hysteresis	V_{LVRH}		50	100	150	mV	—
1.12	Pull-up Current	I_{LVRUP}	V_{LVR} = 2.5V	5	10	15	µA	—
1.13	Output Resistance in reset condition	R_{LVR}	V_{LVR} = 2.5V	200	370	500	Ω	—
1.14	Input Low Voltage	V_{ILLVR}	—	0	—	0.3 x V_{DD}	V	—
1.15	Input High Voltage	V_{IHLVR}	—	0.7 x V_{DD}	—	V_{DD}	V	—

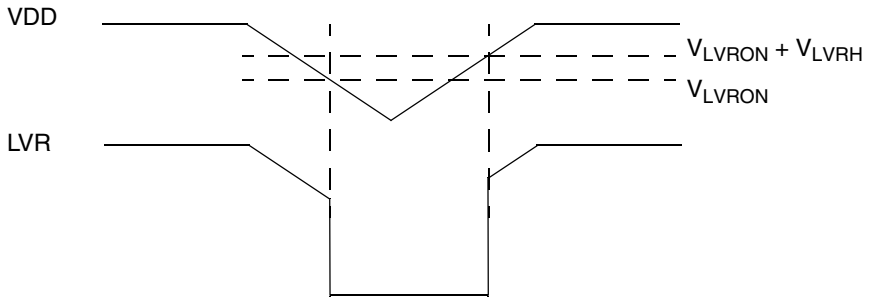


Figure 11. Low Voltage Reset Waveform

14 Oscillator

Typical values reflect average measurements at 6V ≤ V_{SUP} ≤ 16V, V_{SS} = 0V, T_J = –40°C to +125°C, unless otherwise noted

Table 8. Oscillator Specifications

Characteristic		Symbol	Test Condition and Comments	Min	Typ	Max	Unit	Type
Pins XTAL1, XTAL2								
8.0	Input Capacitance	C_{XTAL1}	V_{XTAL1} = 2.5V	—	5	—	pF	—
8.1	Voltage gain V_{XTAL2} / V_{XTAL1}	A_{OSC}	V_{XTAL1} = 2.5V	—	25	—	—	—
8.3	Clock input level	V_{XTAL1}	This level ensures the circuit operation with an 8 MHz clock. It is applied through a capacitive coupling. A 1MΩ resistor connected between XTAL1 and XTAL2 biases the oscillator input.	1.5	—	V_{DD}	Vpp	—

15 Tag Reader

Typical values reflect average measurements at 6V ≤ V_{SUP} ≤ 16V, V_{SS} = 0V, T_J = –40°C to +125°C, unless otherwise noted

Table 9. Tag Reader Specifications

Parameter		Symbol	Test Conditions and Comments	Min	Typ	Max	Unit	Type
Demodulator (pin RD)								
2.0	Input Voltage Range	V_{INRD}	—	3	4	5	V	—
2.2	Input Modulation Frequency	F_{MOD}	—	0.5	4	8	kHz	—
2.3	Demodulator Sensitivity	V_{SENSE1}	6.5V ≤ V_{SUP} ≤ 16V Sensitivity is measured in the following application conditions: $I_{ANTENNA}$ = 50mA peak, V_{RD} = 4V peak, C_{EXT} = 10nF, and square wave modulation F_{MOD} = F_{TD1}/32. See Figure 12	—	5	15	mV	—
2.31	Demodulator Sensitivity	V_{SENSE2}	6V ≤ V_{SUP} < 6.5V The sensitivity is measured in the following application conditions: $I_{ANTENNA}$ = 50mA peak, V_{RD} = 4V peak, C_{EXT} = 10nF, and square wave modulation F_{MOD} = F_{TD1}/32 See Figure 12	—	7	30	mV	—
2.4	Demodulation Delay	t_{Demod}	Configuration C Not including the delay due to the slew rate of the K output for configurations A and B See figure 12	—	7.5	10	µs	—
2.5	After Write Pulse Settling Time	$t_{Settling1}$	—	—	394	400	µs	—
2.6	Recovery Time after wake-up or reset from clock stable to demodulator valid output	$t_{Settling2}$	Clock stable condition implies V_{XTAL1} meets the specification (see page 15).	—	646	700	µs	—
Drivers (pins TD1, TD2)								
3.5	Output Carrier Frequency to Crystal Frequency Ratio	$R_{FTD/FXTAL}$	—	—	64	—	—	—
3.0	Turn on/off Delay	$t_{on/off}$	—	—	—	250	ns	—
3.1	Driver1/2 Low Side Out. Resistance	R_{TDL}	I_{LOAD} = 150mA DC	—	2.4	4	Ω	—
3.2	Driver1/2 High Side Out. Resistance	R_{TDH}	I_{LOAD} = -150mA DC	—	2.1	4	Ω	—

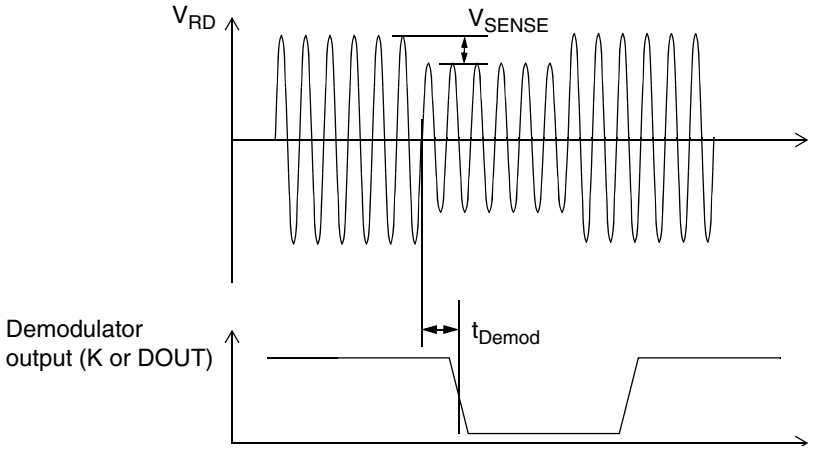


Figure 12. Demodulator Parameters Definition

16 ISO 9141 Interface

Typical values reflect average measurements at $6V \le V_{SUP} \le 16V$, $V_{SS} = 0V$, $T_J = –40°C$ to $+125°C$, unless otherwise noted

Table 10. ISO 9141 Interface Specifications

Parameter		Symbol	Test Conditions and Comments	Min	Typ	Max	Unit	Type
Receiver (pins K and AM)								
4.0	Input Low Voltage	V_{IL}	—	—	—	0.3 x V_{SUP}	V	—
4.1	Input High Voltage	V_{IH}	—	0.65 x V_{SUP}	—	40	V	—
4.2	Input Hysteresis Voltage	V_{HY1}	—	0.4	0.65	1.3	V	—
4.3	Biasing Current	I_B	$0V \le V_{IN} \le 16V$	1	3	5	µA	—
4.31	Input Current	I_{BM}	$-3 \le V_{IN} < 0$	–2	–1	—	mA	—
4.4	K to Rx delay	tdkrx	—		2	10	µs	—
Driver (pin K)								
5.0	Output Falling Edge Slew Rate	SR_F	$R_{Pull-up} = 510\Omega$, Calculated from 20% to 80% of the output swing.	3.5	5	6.5	V/µs	—
5.1	Output Rising Edge Slew Rate	SR_R		3.5	5	6.5	V/µs	—
5.2	Rise Fall Slew Rates Symmetry	$SR_{SYMETRY}$		–1	0	1	V/µs	—
5.3	Output Low Voltage	V_{OLK}	$I_{LOAD} = 25mA$	—	1.1	1.4	V	—
5.4	Input Current (driver switched on or off)	I_{IK}	$–3V \le V_{IN} \le 0V$	–2	—	0	mA	—
5.5	Current Limitation Threshold	I_L	$0V \le V_{IN} \le 40V$	35	50	65	mA	—
5.6	Thermal Shutdown Threshold	TH_{SDWN}	—	130	150	170	°C	—

17 Digital I/O

Typical values reflect average measurements at 6V ≤ V_{SUP} ≤ 16V, V_{SS} = 0V, T_J = –40°C to +125°C, unless otherwise noted

Table 11. Digital I/O Specifications

Characteristic		Symbol	Test Condition and Comments	Min	Typ	Max	Unit	Type
Input (pins MODE1, MODE2, AM, TX)								
6.0	Input Low Voltage	V_{ILD}	—	0	—	0.3 x V_{DD}	V	—
6.1	Input High Voltage	V_{IHD}	—	0.7 x V_{DD}	—	V_{DD}	V	—
6.2	Input Hysteresis Voltage	V_{HD}	—	.24	.7	1	V	—
Output (pins DOUT,RX)								
7.0	Output Low Voltage	V_{OL}	I_{LOAD} = 500uA	0	0.5	0.2 x V_{DD}	V	—
7.1	Output High Voltage	V_{OH}	I_{LOAD} = -500uA	0.8 x V_{DD}	4.6	V_{DD}	V	—
7.2	Fall/Rise Time	$t_{F/R}$	C_{LOAD}=10pF, Calculated from 10% to 90% of the output swing	—	—	150	ns	—

18 Pin Definition and Function

The internal circuits connected to the pins of the device are shown in Figures 13 – 23, including the diodes used for ESD protection.

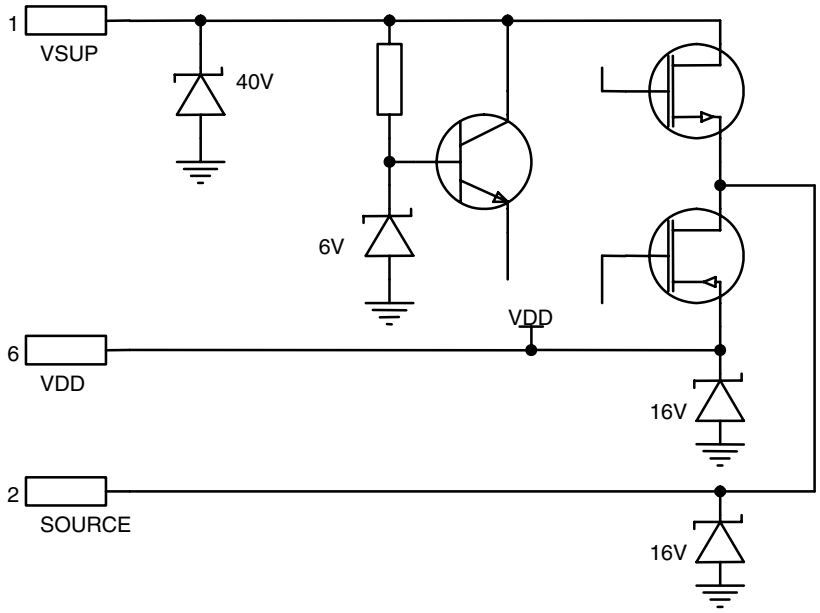


Figure 13. VSUP, VDD, and Source Internal Circuits

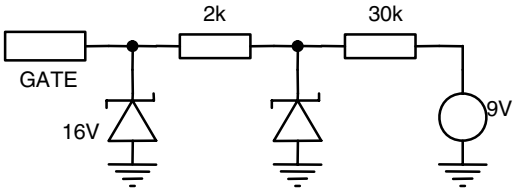


Figure 14. GATE Internal Circuits

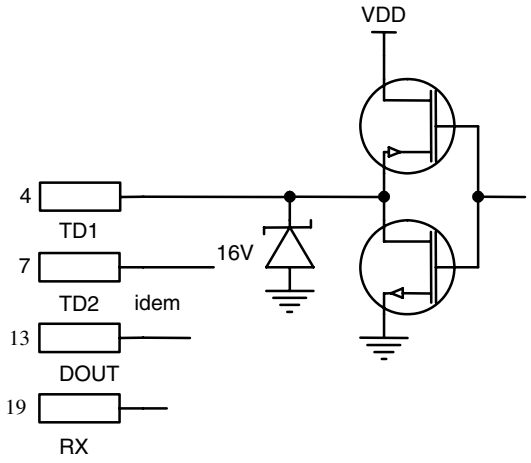


Figure 15. TD1, TD2, DOUT, and RX Internal Circuits

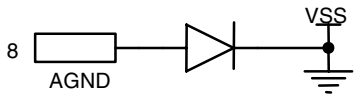


Figure 16. AGND Internal Circuits

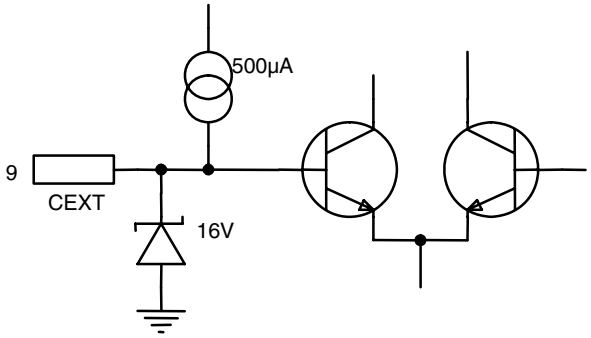


Figure 17. CEXT Internal Circuits

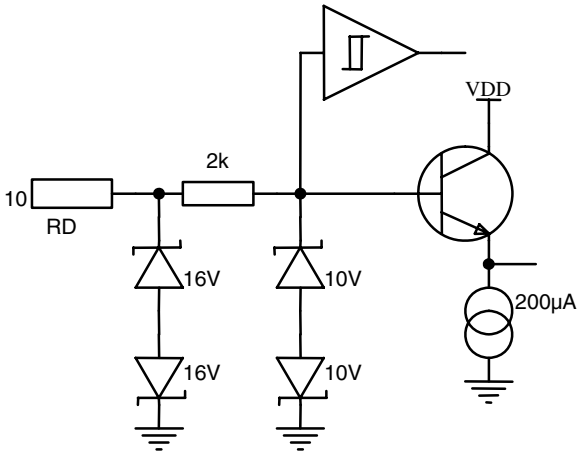


Figure 18. RD Internal Circuits

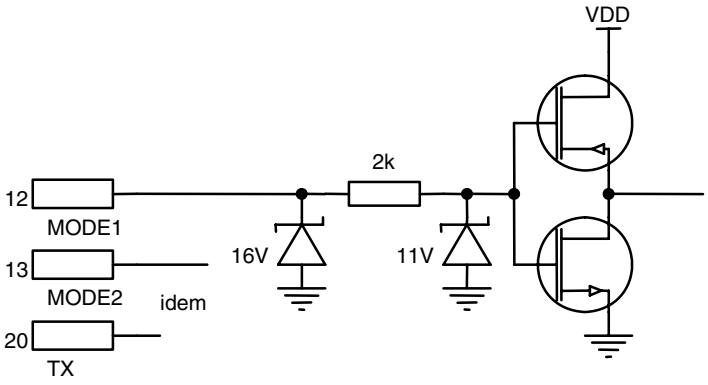


Figure 19. MODE1, MODE2, and TX Internal Circuits

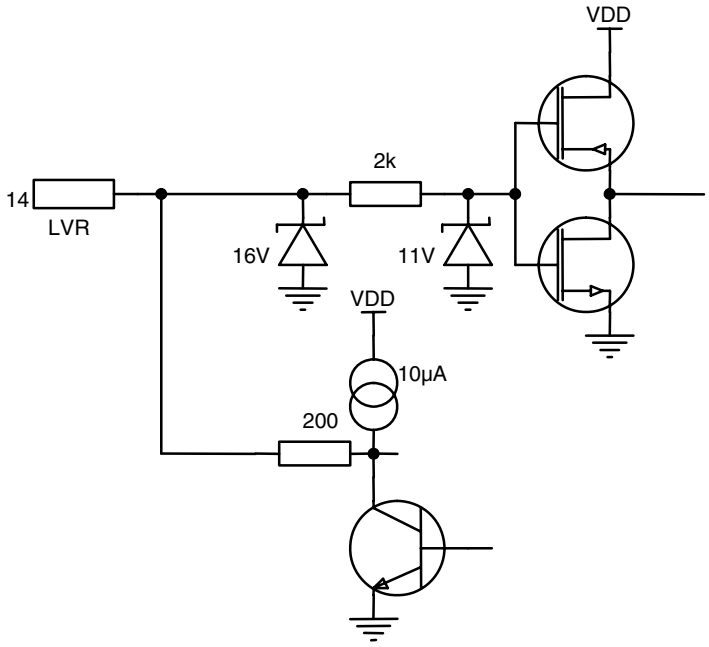


Figure 20. LVR Internal Circuits

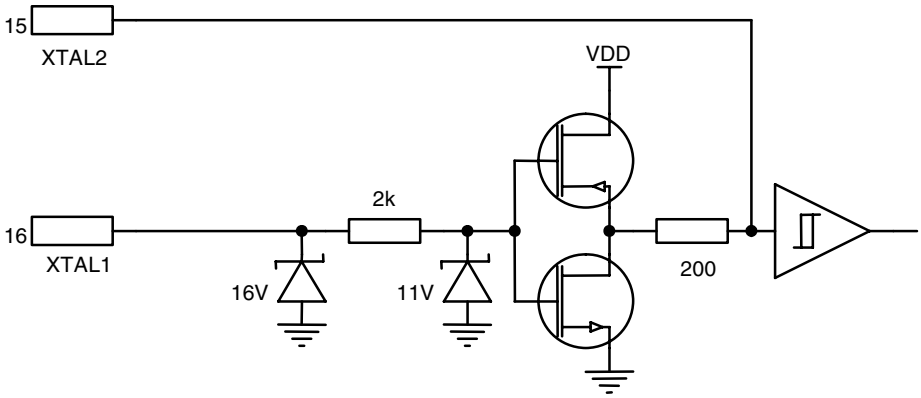


Figure 21. XTAL2 and XTAL1 Internal Circuits

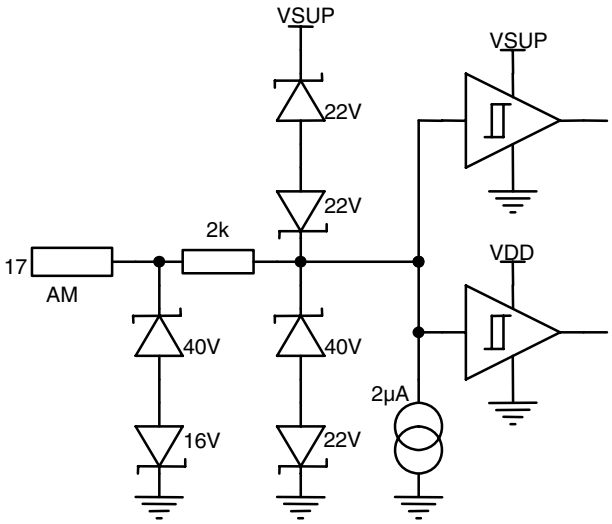


Figure 22. AM Internal Circuits

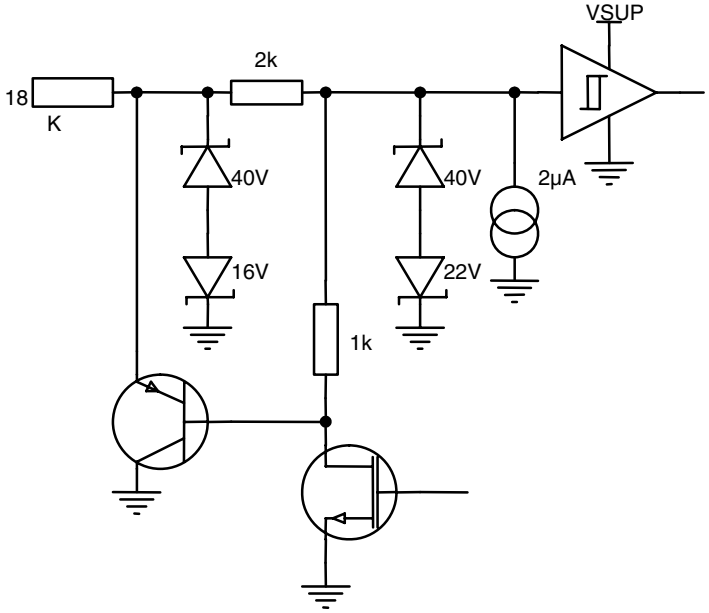
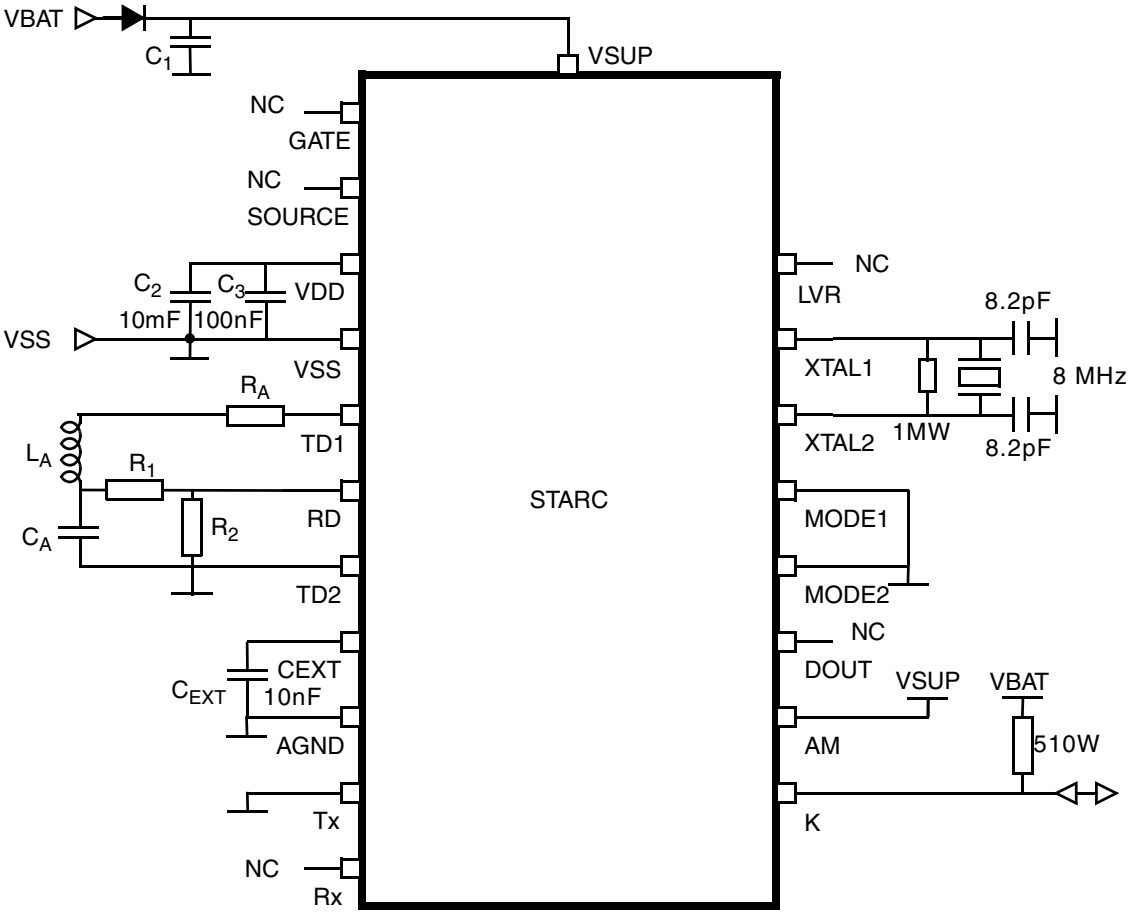


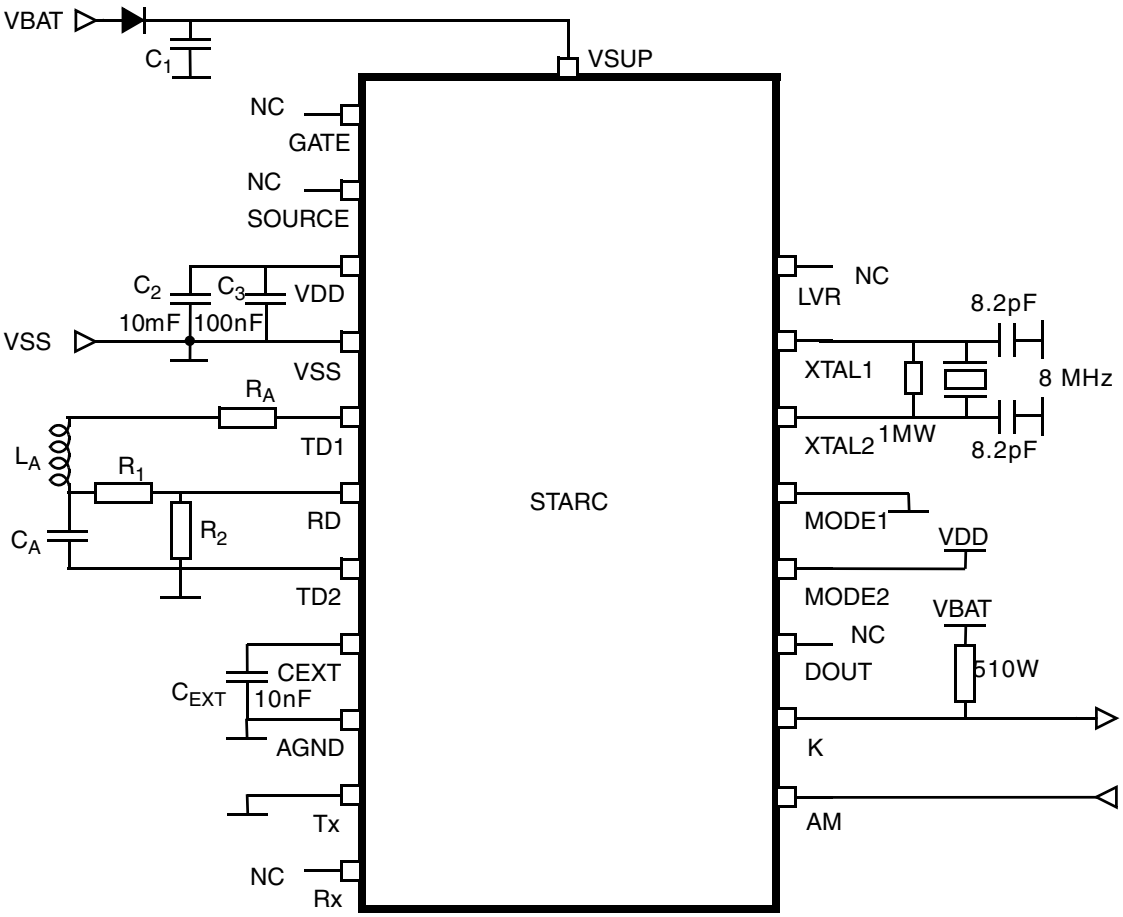
Figure 23. K Internal Circuits

19 Application Schemes



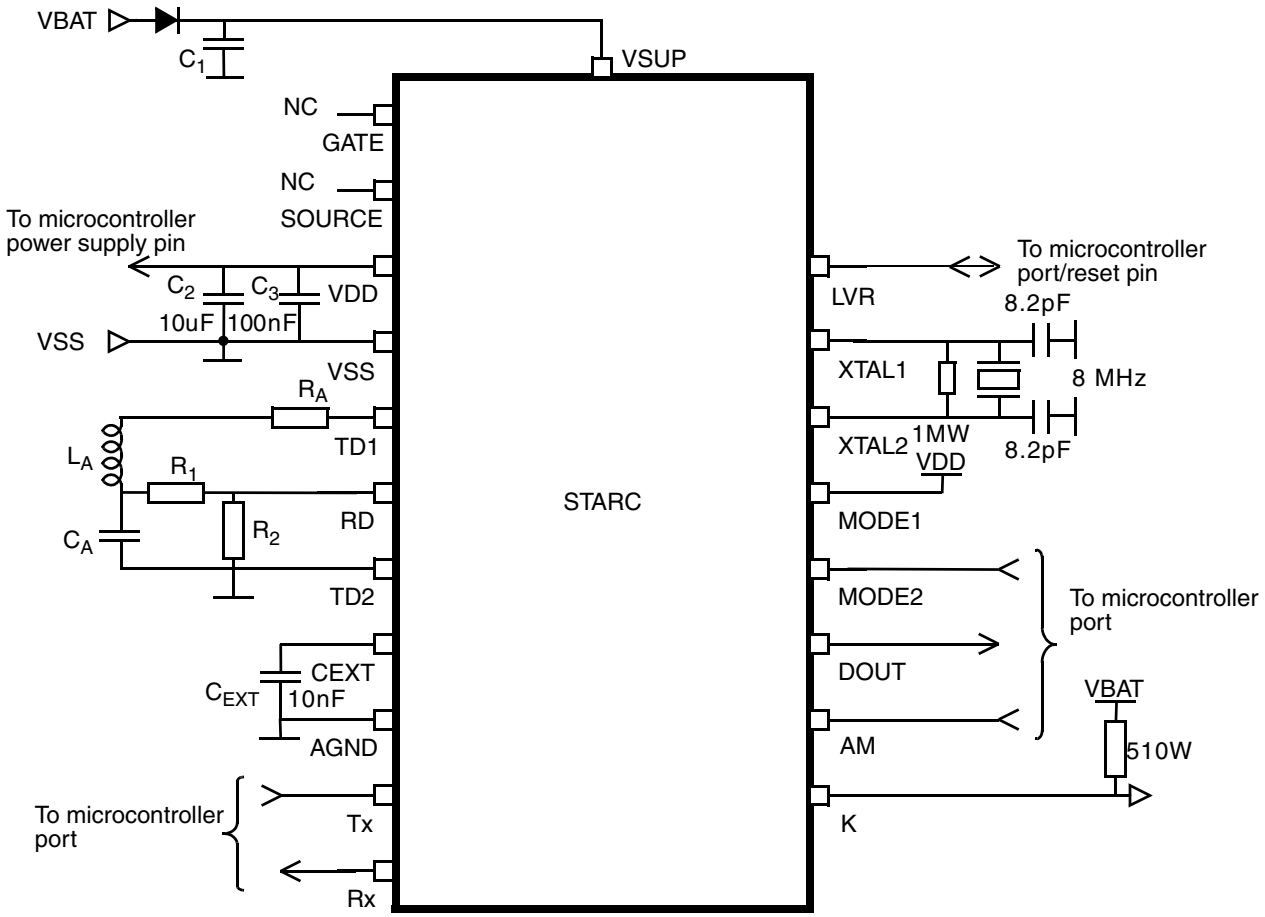
Note: If no external MOS transistor is necessary to increase the voltage regulator current capability, the pins GATE and SOURCE must be left unconnected. In this configuration, the outputs Rx and DOUT force a low level. C1 is not required for the STARC functionality and only acts as a reservoir of energy. To preserve the demodulator sensitivity, CEXT and R2 should be connected to AGND and VSS connected to AGND using a low resistance path.

Figure 24. Standalone Configuration with One-Wire Bus



Note: If no external MOS transistor is necessary to increase the voltage regulator current capability, the pins GATE and SOURCE must be left unconnected. C_1 is not required for the STARC functionality and only acts as a reservoir of energy. To preserve the demodulator sensitivity, C_{EXT} and R_2 should be connected to AGND and VSS connected to AGND using a low resistance path.

Figure 25. Standalone Configuration with Two-Wires Bus



Note: If no external MOS transistor is necessary to increase the voltage regulator current capability, the pins GATE and SOURCE must be left unconnected. C_1 is not required for the STARC functionality and only acts as a reservoir of energy. To preserve the demodulator sensitivity, C_{EXT} and R_2 should be connected to AGND and VSS connected to AGND using a low resistance path.

Figure 26. Direct Connection to a Microcontroller